

Thickness measuring instrument FLATSCAN WMT for Wafer Mounting Technology

Non contact thickness measuring of glass and cementing layer

FLATSCAN WMT provides highly accurate, non contact thickness measuring of all kinds of transparent objects. For use in Wafer Mounting Technology FLATSCAN is able to measure the common thickness of glass substrate and cementing layer.

High resolution thickness sensor guarantees precise measurements

Basis of the measuring instrument is the high resolution thickness sensor CAS for transparent objects.

Comfortable Windows-Software allows single measurements and automatic thickness mappings

The comfortable Windows software controls the measuring and offers graphical and numerical data evaluation and representation, for instance 3D-representation of thickness distributions and sectional views. The measuring results can be stored in freely configurable measuring protocols or in ASCII-Files.

The standard measuring field is (150 x 150) mm. Any other measuring field is possible.

Technical Data

Positioning resolution:	10 μm
Measuring accuracy:	$\pm 1 \mu\text{m}$
Measuring field:	(150 x 150) mm
Free working distance:	$22 \pm 5 \text{ mm}$
Measuring wavelength:	670 nm
Software:	32 Bit, runs under Windows
	95/98/NT/2000

